HOSTAFORM® C 9021 SW

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Chemical abbreviation according to ISO 1043-1: POM-KD10
Molding compound ISO 29988-POM-K,KD10,GNRS2,3-2
POM copolymer Injection molding type, special modified with anti-friction additives for prevention of squeaking noise; good chemical resistance to solvents, fuel and strong alkalis as well as good hydrolysis resistance; high resistance to thermal and oxidative degradation. UL-registration in natural and black and a thickness more than 1.5 mm as UL 94 HB. Burning rate ISO 3795 and FMVSS 302 < 100 mm/min for a thickness more than 1,5 mm. Ranges of applications: For sliding combinations with low wear and low coefficient of friction, prevents squeaking noise. UL = Underwriters Laboratories (USA) FMVSS = Federal Motor Vehicle Safety Standard (USA)

Product information

Resin Identification	POM-KD10	ISO 1043
Part Marking Code	>POM-KD10<	ISO 11469

Rheological properties

Melt volume-flow rate	6.5	cm^3/10min	ISO 1133
Temperature	374	°F	
Load	4.76	lb	
Molding shrinkage, parallel	2.1[1]	%	ISO 294-4, 2577
Molding shrinkage, normal	1.7[1]	%	ISO 294-4, 2577

[1]: @ 195°C

Typical mechanical properties

Tensile modulus	413000	psi	ISO 527-1/-2
Tensile stress at yield, 50mm/min	7700	psi	ISO 527-1/-2
Tensile strain at yield, 50mm/min	7	%	ISO 527-1/-2
Nominal strain at break	16	%	ISO 527-1/-2
Tensile creep modulus, 1h	348000	psi	ISO 899-1
Tensile creep modulus, 1000h	174000	psi	ISO 899-1
Charpy impact strength, 23°C	42.8	$ftlb/in^2$	ISO 179/1eU
Charpy impact strength, -30°C	40.4	$ftlb/in^2$	ISO 179/1eU
Charpy notched impact strength, 23°C	1.9	$ftlb/in^2$	ISO 179/1eA
Charpy notched impact strength, -30°C	1.9	$ftlb/in^2$	ISO 179/1eA
Ball indentation hardness, H 358/30	19600	psi	ISO 2039-1

Thermal properties

Melting temperature, 10°C/min	331	°F	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	176	°F	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	0.67	E-4/°F	ISO 11359-1/-2

Flammability

Burning Behav. at 1.5mm nom. thickn.	HB	class	IEC 60695-11-10
Thickness tested	0.0630	in	IEC 60695-11-10
Burning Behav. at thickness h	HB	class	IEC 60695-11-10
Thickness tested	0.1252	in	IEC 60695-11-10
UL recognition	yes		UL 94
FMVSS Class	B		ISO 3795 (FMVSS 302)
Burning rate, Thickness 1 mm	3.74	in/min	ISO 3795 (FMVSS 302)

HOSTAFORM® C 9021 SW

HOSTAFORM®

Electrical properties

Relative permittivity, 100Hz	4.1		IEC 62631-2-1
Relative permittivity, 1MHz	4.1		IEC 62631-2-1
Dissipation factor, 100Hz	35	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	75	E-4	IEC 62631-2-1
Volume resistivity	1E12	Ohm.m	IEC 62631-3-1
Surface resistivity	1E14	Ohm	IEC 62631-3-2
Comparative tracking index	600		IEC 60112

Physical/Other properties

Humidity absorption, 2mm	0.2	%	Sim. to ISO 62
Water absorption, 2mm	1.2	%	Sim. to ISO 62
Density	0.0513	lb/in^3	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	212	°F
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	392	°F
Min. melt temperature	374	°F
Max. melt temperature	410	°F
Max. screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	212	°F
Min. mold temperature	176	°F
Max. mold temperature	248	°F
Hold pressure range	8700 - 17400	psi
Hold Pressure Time (h is the max. wall thickness of the part in mm)	2h^2-3	s
Back pressure	290	psi

Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Bosch	N28 BN22-O015	Natural
Bosch	N28 BN22-O015	Black
Continental	TST N 055 54.23	
Hyundai	MS237-05 Type A-2	
Nissan	POM(0xx)-Ixx-1	

Characteristics

Processing	Injection Molding, Other Extrusion
Additives	Release agent
Special characteristics	Low wear / Low friction

HOSTAFORM® C 9021 SW

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Additional information

Injection molding

Preprocessing

General drying is not necessary due to low moisture absorption of the resin.

In case of bad storage conditions (water contact or condensed water) the use of a recirculating air dryer (100 to 120 °C / max. 40 mm layer / 3 to 6 hours) is recommended.

Max. Water content 0,2 %

Processing

Standard injection moulding machines with three phase (15 to 25 D) plasticating screws will fit.

Postprocessing

Conditioning e.g. moisturizing is not necessary.

Processing Notes

Pre-Drying

Drying is not normally required. If material has come in contact with moisture through improper storage or handling or through regrind use, drying may be necessary to prevent splay and odor problems.

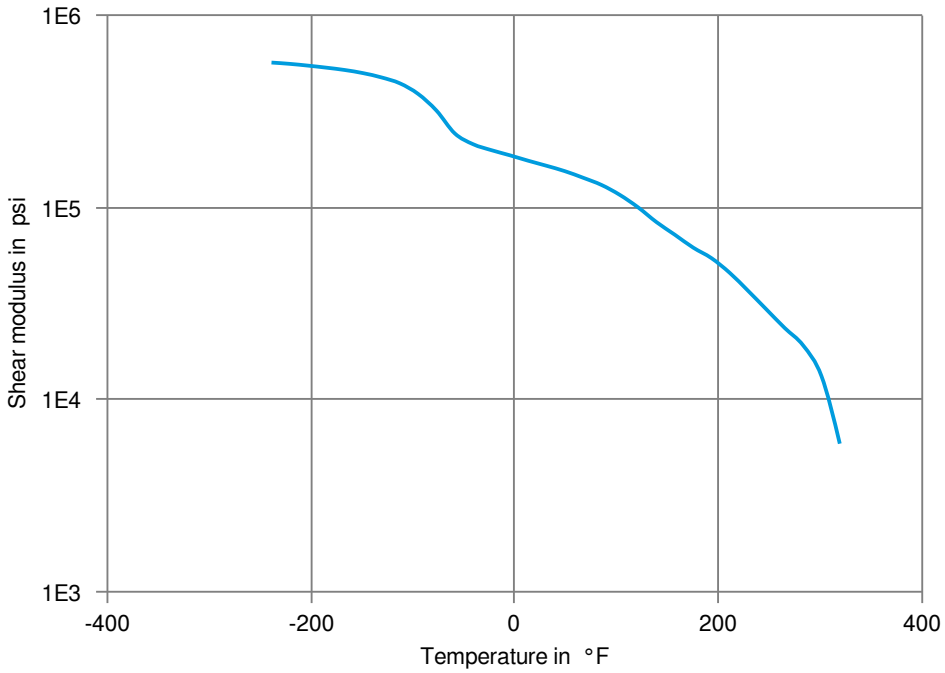
Storage

The product can then be stored in standard conditions until processed.

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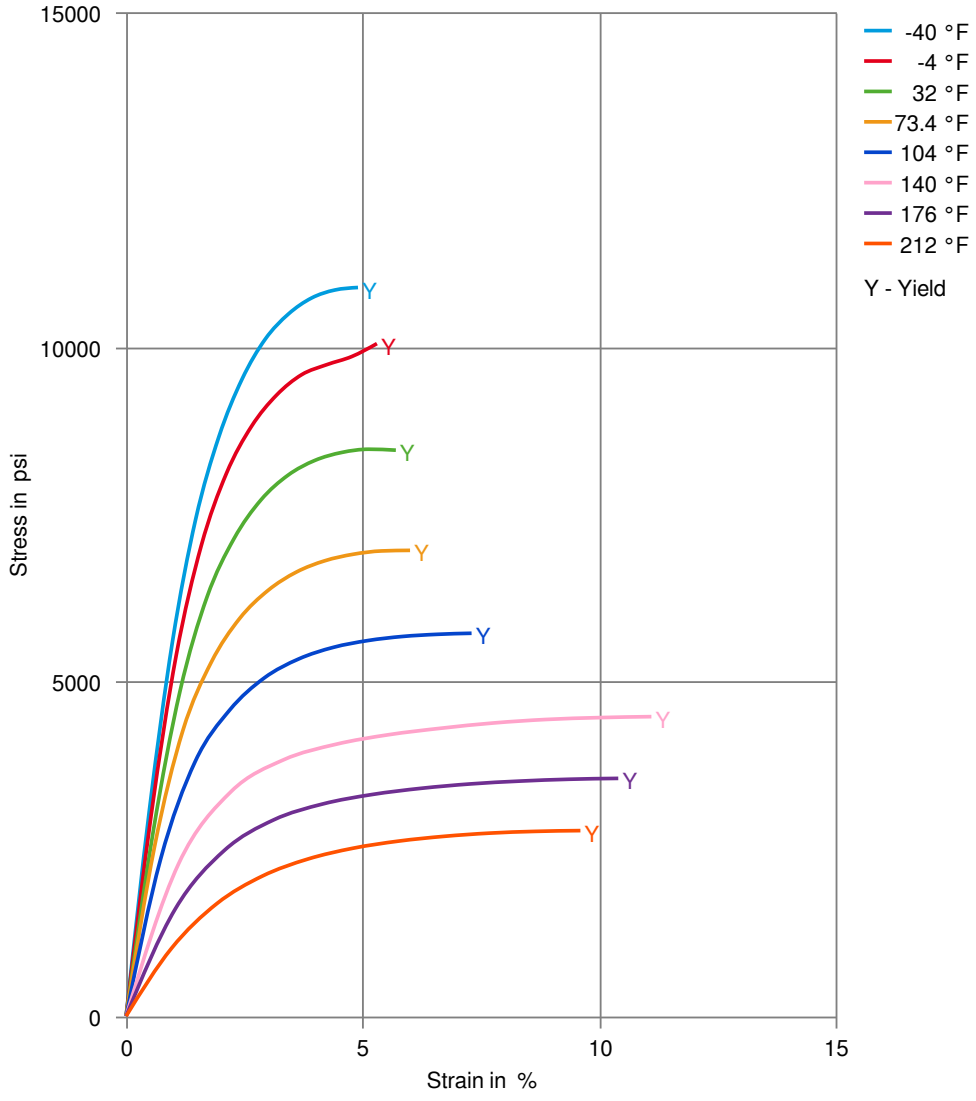
Dynamic Shear modulus-temperature



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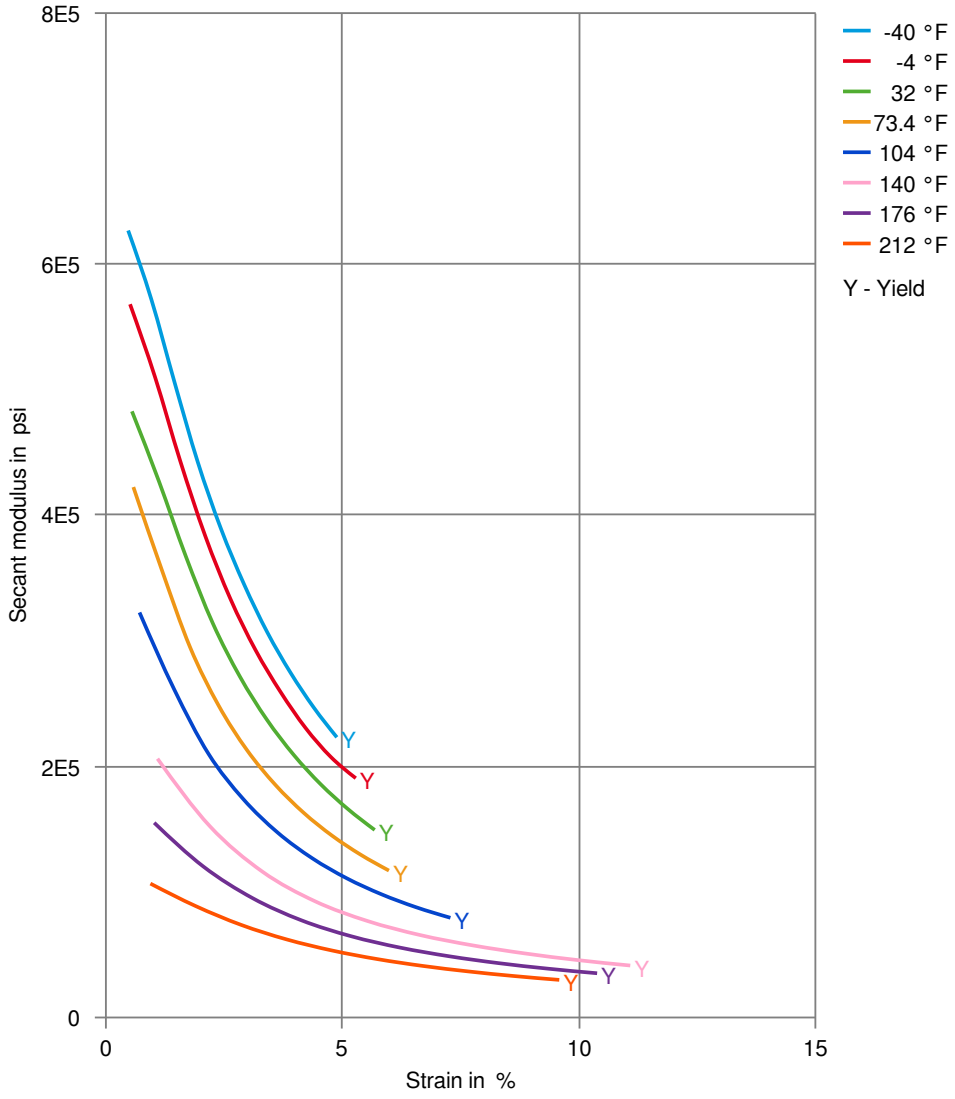
Stress-strain



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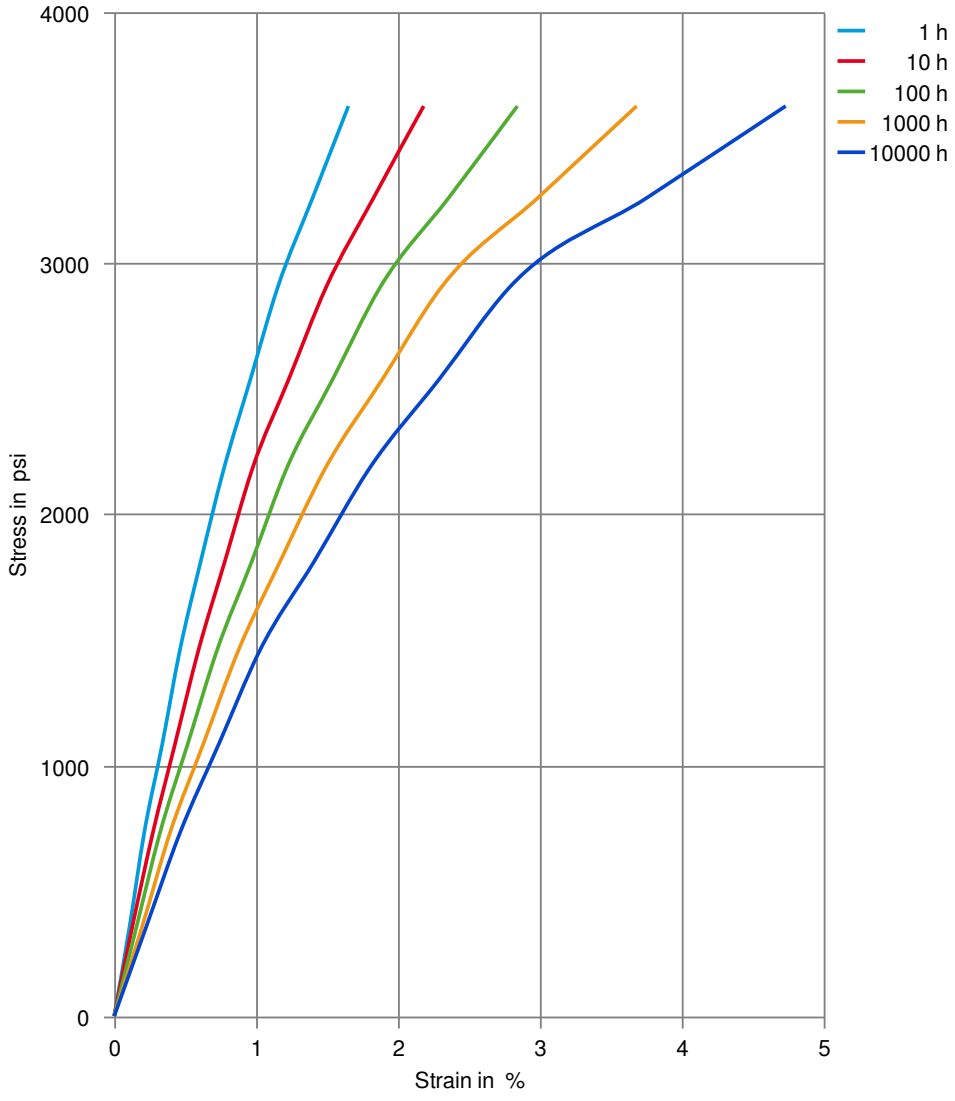
Secant modulus-strain



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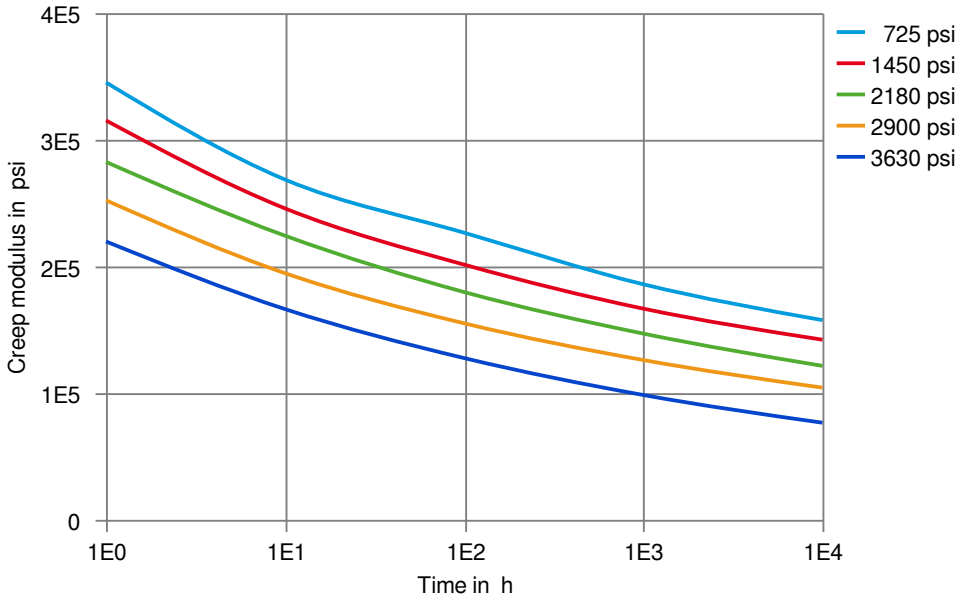
Stress-strain (isochronous) 73.4 °F



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Creep modulus-time 73.4 °F



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